
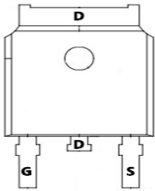
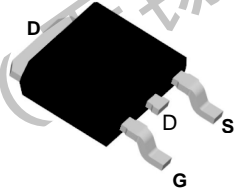
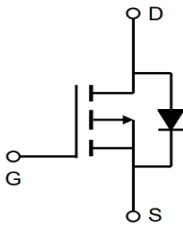


TM60P02D

P-Channel Enhancement Mosfet

<p>General Description</p> <ul style="list-style-type: none"> • Low R_{DS(ON)} • RoHS and Halogen-Free Compliant <p>Applications</p> <ul style="list-style-type: none"> • Load switch • PWM 	<p>General Features</p> <p>V_{DS} = -20V I_D = -60A</p> <p>R_{DS(ON)} = 6.5mΩ(typ.)@V_{GS} = -4.5V</p> <p>100% UIS Tested 100% R_g Tested</p> 
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D:TO-252-3L

Marking: 60P02

Absolute Maximum Ratings (T_C = 25°C Unless Otherwise Noted)

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	-20	V
V _{GS}	Gate-Source Voltage	±12	V
I _D @T _C =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	-60	A
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ 10V ¹	-36	A
I _{DM}	Pulsed Drain Current ²	-150	A
P _D @T _C =25°C	Total Power Dissipation ³	70	W
T _{STG}	Storage Temperature Range	-55 to 175	°C
T _J	Operating Junction Temperature Range	-55 to 175	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction-ambient ¹	---	62	°C/W
R _{θJC}	Thermal Resistance Junction-Case ¹	---	6.6	°C/W

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Electrical Characteristics (T_J=25°C unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D = -250μA	-20	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = -20V, V _{GS} = 0V,	-	-	-1	μA
I _{GSS}	Gate to Body Leakage Current	V _{DS} =0V, V _{GS} = ±12V	-	-	±100	nA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = -250μA	-0.5	-0.7	-1.0	V
R _{DS(on)}	Static Drain-Source on-Resistance <small>note3</small>	V _{GS} = -4.5V, I _D = -15A	-	6.5	7.5	mΩ
		V _{GS} = -2.5V, I _D = -12A	-	8.8	11	
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} = -10V, V _{GS} = 0V, f = 1.0MHz	-	3520	-	pF
C _{oss}	Output Capacitance		-	505	-	pF
C _{rss}	Reverse Transfer Capacitance		-	440	-	pF
Q _g	Total Gate Charge	V _{DS} = -10V, I _D = -15A, V _{GS} = -4.5V	-	46	-	nC
Q _{gs}	Gate-Source Charge		-	7.3	-	nC
Q _{gd}	Gate-Drain("Miller") Charge		-	10	-	nC
Switching Characteristics						
t _{d(on)}	Turn-on Delay Time	V _{DD} = -10V, I _D = -14A, R _{GEN} = 2.7Ω, V _{GS} = -10V	-	8	-	ns
t _r	Turn-on Rise Time		-	59	-	ns
t _{d(off)}	Turn-off Delay Time		-	111	-	ns
t _f	Turn-off Fall Time		-	43	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I _S	Maximum Continuous Drain to Source Diode Forward Current		-	-	-60	A
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	-240	A
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} = 0V, I _S = -20A	-	-	-1.2	V
trr	Reverse Recovery Time	T _J = 25°C, I _{SD} = -15A,	-	18	-	ns
Qrr	Reverse Recovery Charge	V _{GS} = 0V di/dt = -100A/μs	-	7.7	-	nC

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition: T_J=25°C, V_{DD}=-10V, V_G=-10V, R_G=5.9Ω, L=0.5mh, I_{AS}=-13.2A

3. Pulse Test: Pulse Width≤300μs, Duty Cycle≤0.5%

Typical Performance Characteristics

Figure 1: Output Characteristics

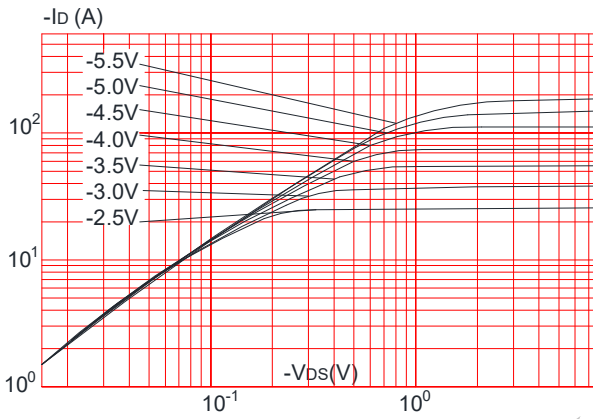


Figure 2: Typical Transfer Characteristics

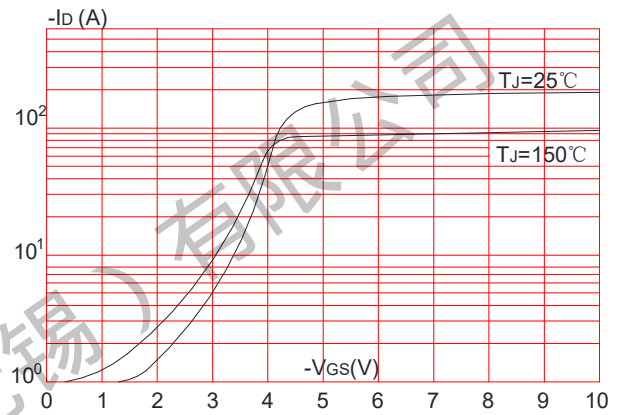


Figure 3: On-resistance vs. Drain Current

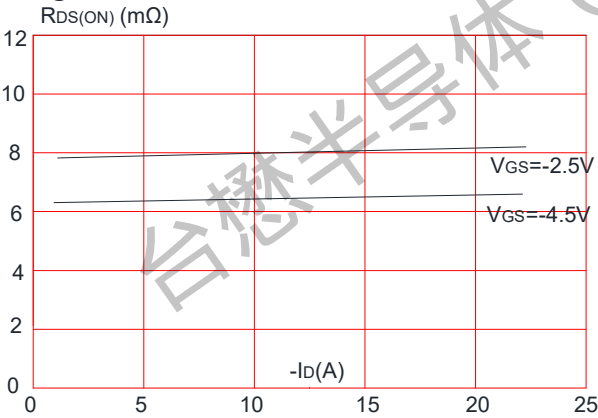


Figure 4: Body Diode Characteristics

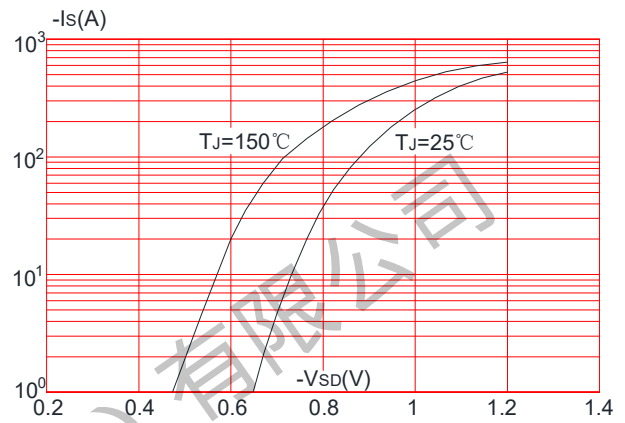


Figure 5: Gate Charge Characteristics

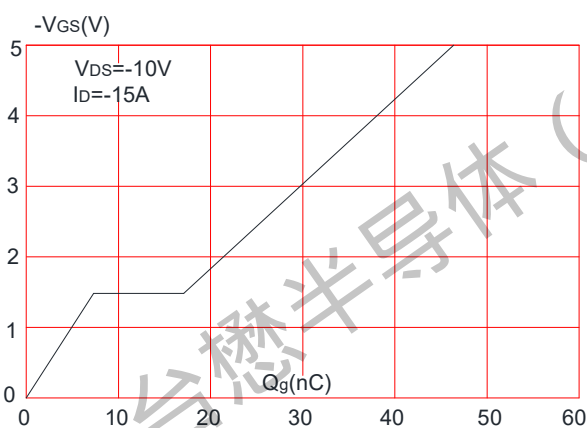
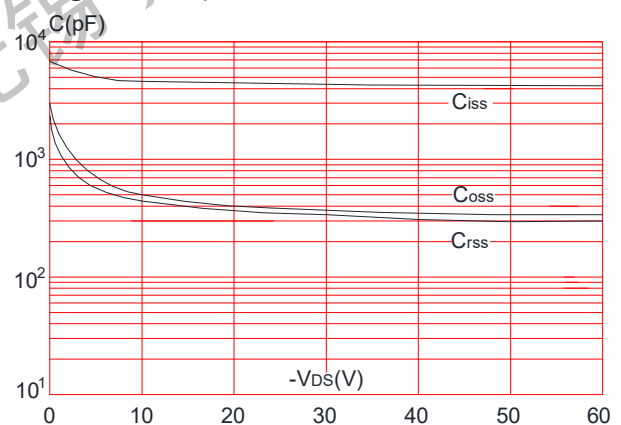


Figure 6: Capacitance Characteristics





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Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

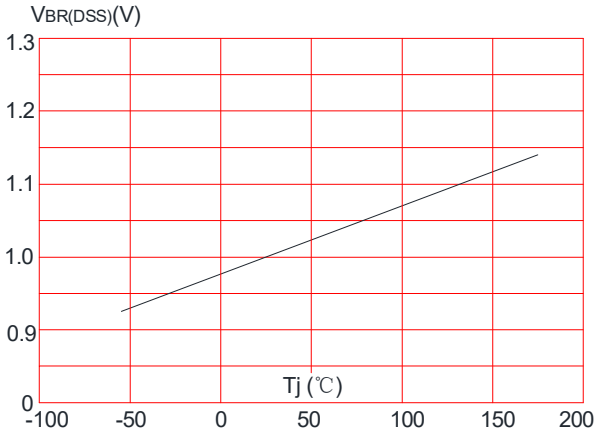


Figure 8: Normalized on Resistance vs. Junction Temperature

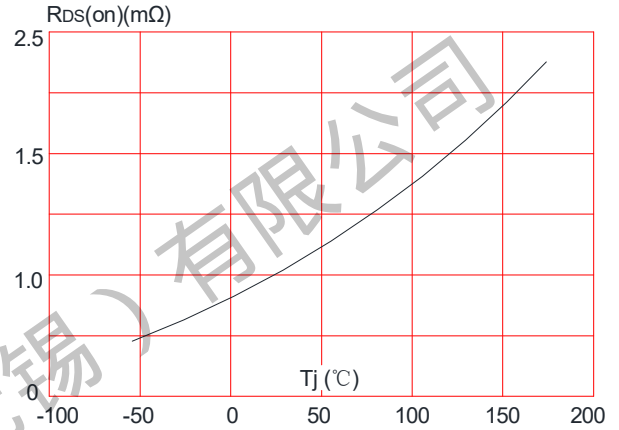


Figure 9: Maximum Safe Operating Area

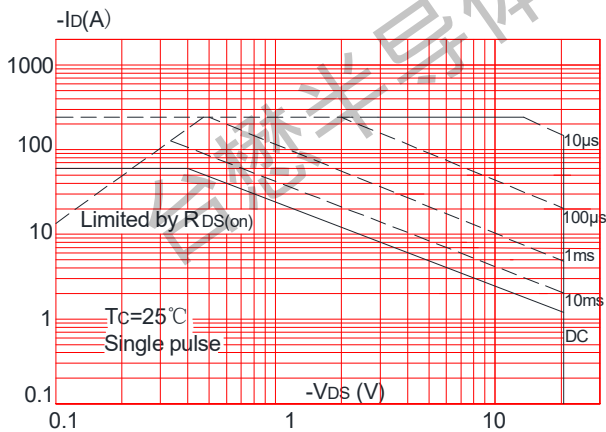


Figure 10: Maximum Continuous Drain Current vs. Case Temperature

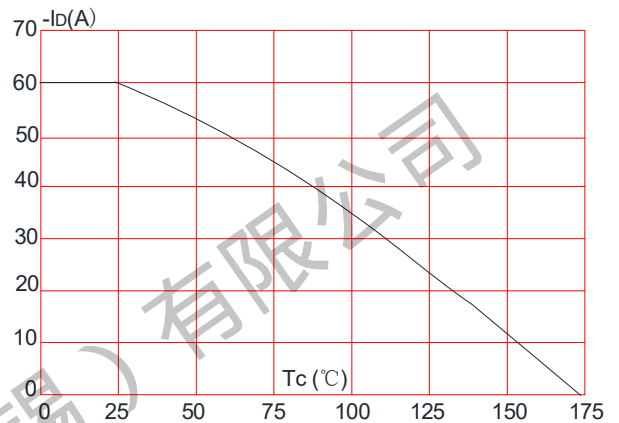
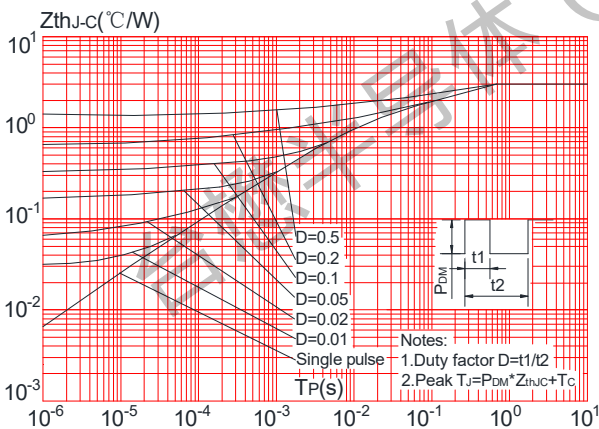


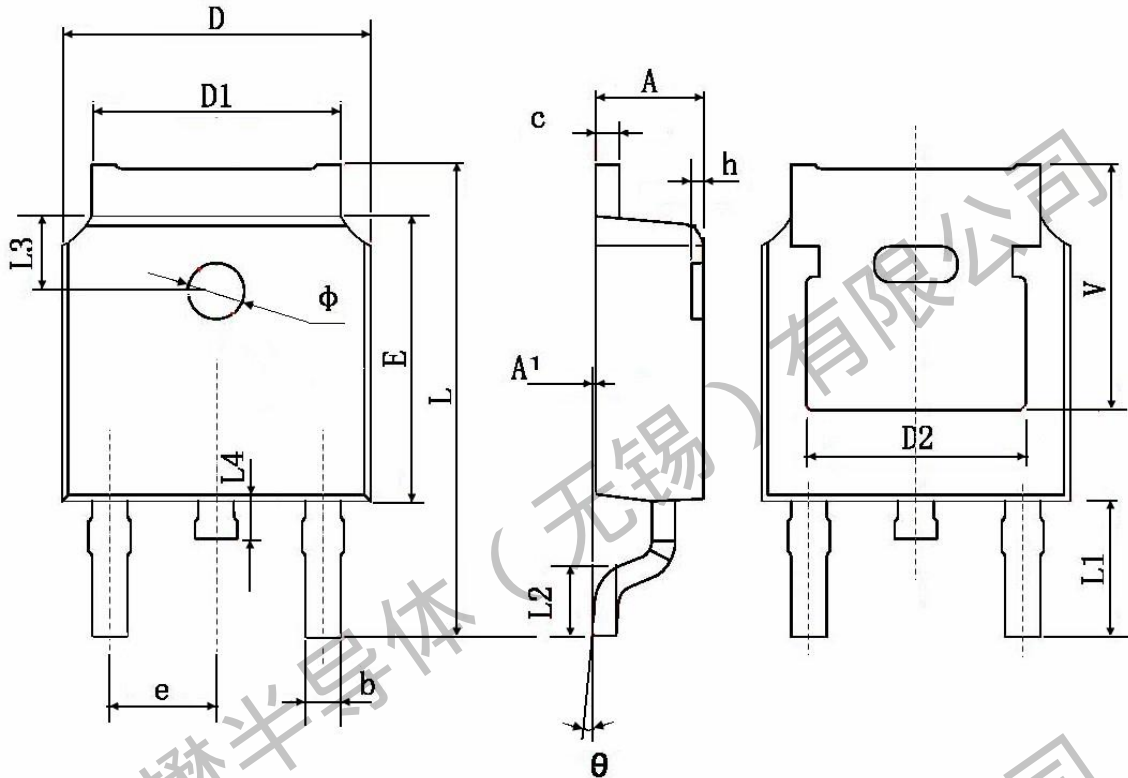
Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Case



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Package Mechanical Data: TO-252-3L



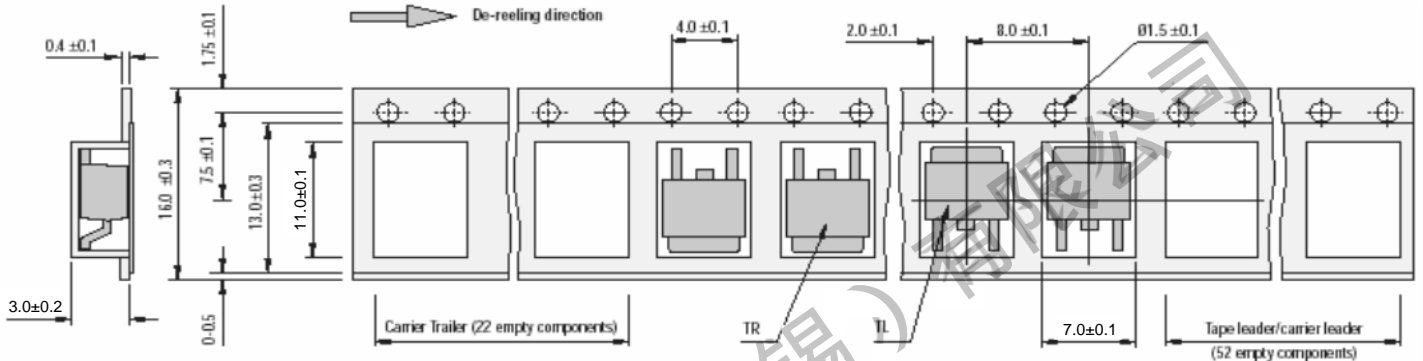
Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 TYP.		0.190 TYP.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 TYP.		0.114 TYP.	
L2	1.400	1.700	0.055	0.067
L3	1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039
ϕ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
v	5.350 TYP.		0.211 TYP.	



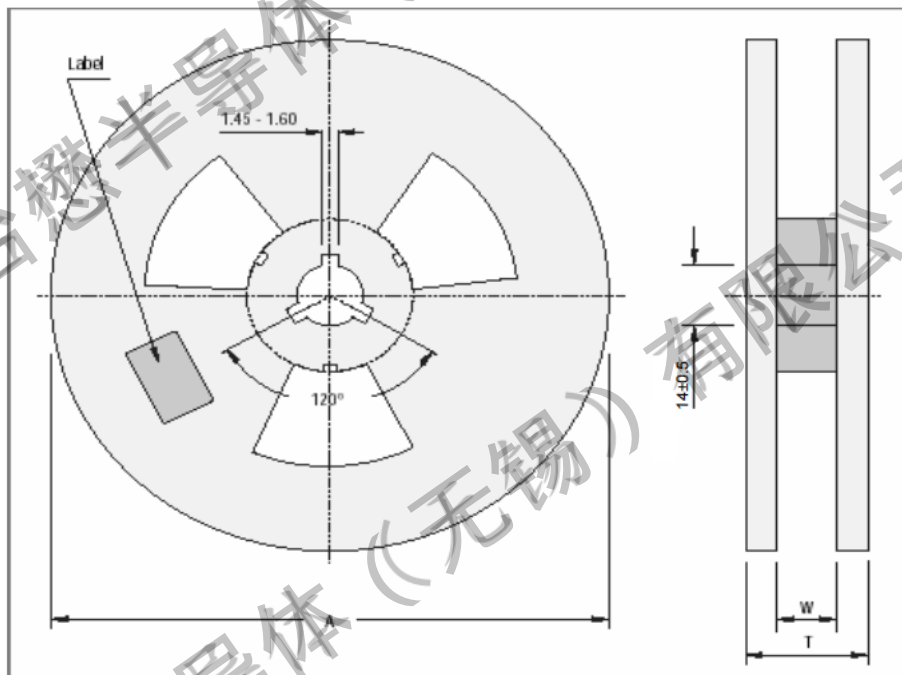
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P-Channel Enhancement Mosfet

TO-252-3L Embossed Carrier Tape



TO-252-3L Reel



All Dimensions are in mm.

Reel Specifications				
Package	Tape Width	Reel Dia. A - Max	Inside Thickness W	Reel Thickness T - max
TO-252-3L	16	330	18.0 ±1.5	20

Packaging Information

REEL	Reel Size	Box	Box Size(mm)	Carton	Carton Size(mm)	G.W.(kg)
2,500 pcs	13 inch	5,000 pcs	355×370×50	25,000 pcs	380×275×380	

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Revision history:

Date	Rev	Description	Page
2023.05.09	23.05	Original	